



Welcome to [E-XFL.COM](https://www.e-xfl.com)

### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	216000
Number of Logic Elements/Cells	3780000
Total RAM Bits	514867200
Number of I/O	702
Number of Gates	-
Voltage - Supply	0.825V ~ 0.876V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	2104-BBGA, FCBGA
Supplier Device Package	2104-FCBGA (52.5x52.5)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xcvu13p-2fhgb2104i">https://www.e-xfl.com/product-detail/xilinx/xcvu13p-2fhgb2104i</a>

## Migrating Devices

UltraScale and UltraScale+ families provide footprint compatibility to enable users to migrate designs from one device or family to another. Any two packages with the same footprint identifier code are footprint compatible. For example, Kintex UltraScale devices in the A1156 packages are footprint compatible with Kintex UltraScale+ devices in the A1156 packages. Likewise, Virtex UltraScale devices in the B2104 packages are compatible with Virtex UltraScale+ devices and Kintex UltraScale devices in the B2104 packages. All valid device/package combinations are provided in the Device-Package Combinations and Maximum I/Os tables in this document. Refer to [UG583](#), *UltraScale Architecture PCB Design User Guide* for more detail on migrating between UltraScale and UltraScale+ devices and packages.

# Kintex UltraScale+ FPGA Feature Summary

Table 5: Kintex UltraScale+ FPGA Feature Summary

	KU3P	KU5P	KU9P	KU11P	KU13P	KU15P
System Logic Cells	355,950	474,600	599,550	653,100	746,550	1,143,450
CLB Flip-Flops	325,440	433,920	548,160	597,120	682,560	1,045,440
CLB LUTs	162,720	216,960	274,080	298,560	341,280	522,720
Max. Distributed RAM (Mb)	4.7	6.1	8.8	9.1	11.3	9.8
Block RAM Blocks	360	480	912	600	744	984
Block RAM (Mb)	12.7	16.9	32.1	21.1	26.2	34.6
UltraRAM Blocks	48	64	0	80	112	128
UltraRAM (Mb)	13.5	18.0	0	22.5	31.5	36.0
CMTs (1 MMCM and 2 PLLs)	4	4	4	8	4	11
Max. HP I/O <sup>(1)</sup>	208	208	208	416	208	572
Max. HD I/O <sup>(2)</sup>	96	96	96	96	96	96
DSP Slices	1,368	1,824	2,520	2,928	3,528	1,968
System Monitor	1	1	1	1	1	1
GTH Transceiver 16.3Gb/s	0	0	28	32	28	44
GTY Transceivers 32.75Gb/s <sup>(3)</sup>	16	16	0	20	0	32
Transceiver Fractional PLLs	8	8	14	26	14	38
PCIe Gen3 x16 and Gen4 x8	1	1	0	4	0	5
150G Interlaken	0	0	0	1	0	4
100G Ethernet w/RS-FEC	0	1	0	2	0	4

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTY transceiver line rates are package limited: SFVB784 to 12.5Gb/s; FFVA676, FFVD900, and FFVA1156 to 16.3Gb/s. See [Table 6](#).

# Kintex UltraScale+ Device-Package Combinations and Maximum I/Os

Table 6: Kintex UltraScale+ Device-Package Combinations and Maximum I/Os

Package (1)(2)(4)	Package Dimensions (mm)	KU3P	KU5P	KU9P	KU11P	KU13P	KU15P
		HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY
SFVB784(3)	23x23	96, 208 0, 16	96, 208 0, 16				
FFVA676(3)	27x27	48, 208 0, 16	48, 208 0, 16				
FFVB676	27x27	72, 208 0, 16	72, 208 0, 16				
FFVD900(3)	31x31	96, 208 0, 16	96, 208 0, 16		96, 312 16, 0		
FFVE900	31x31			96, 208 28, 0		96, 208 28, 0	
FFVA1156(3)	35x35				48, 416 20, 8		48, 468 20, 8
FFVE1517	40x40				96, 416 32, 20		96, 416 32, 24
FFVA1760	42.5x42.5						96, 416 44, 32
FFVE1760	42.5x42.5						96, 572 32, 24

## Notes:

- Go to [Ordering Information](#) for package designation details.
- FF packages have 1.0mm ball pitch. SF packages have 0.8mm ball pitch.
- GTY transceiver line rates are package limited: SFVB784 to 12.5Gb/s; FFVA676, FFVD900, and FFVA1156 to 16.3Gb/s.
- Packages with the same last letter and number sequence, e.g., A676, are footprint compatible with all other UltraScale architecture-based devices with the same sequence. The footprint compatible devices within this family are outlined. See the [UltraScale Architecture Product Selection Guide](#) for details on inter-family migration.

# Virtex UltraScale Device-Package Combinations and Maximum I/Os

Table 8: Virtex UltraScale Device-Package Combinations and Maximum I/Os

Package <sup>(1)(2)(3)</sup>	Package Dimensions (mm)	VU065	VU080	VU095	VU125	VU160	VU190	VU440
		HR, HP GTH, GTY	HR, HP GTH, GTY	HR, HP GTH, GTY	HR, HP GTH, GTY	HR, HP GTH, GTY	HR, HP GTH, GTY	HR, HP GTH, GTY
FFVC1517	40x40	52, 468 20, 20	52, 468 20, 20	52, 468 20, 20				
FFVD1517	40x40		52, 286 32, 32	52, 286 32, 32				
FLVD1517	40x40				52, 286 40, 32			
FFVB1760	42.5x42.5		52, 650 32, 16	52, 650 32, 16				
FLVB1760	42.5x42.5				52, 650 36, 16			
FFVA2104	47.5x47.5		52, 780 28, 24	52, 780 28, 24				
FLVA2104	47.5x47.5				52, 780 28, 24			
FFVB2104	47.5x47.5		52, 650 32, 32	52, 650 32, 32				
FLVB2104	47.5x47.5				52, 650 40, 36			
FLGB2104	47.5x47.5					52, 650 40, 36	52, 650 40, 36	
FFVC2104	47.5x47.5			52, 364 32, 32				
FLVC2104	47.5x47.5				52, 364 40, 40			
FLGC2104	47.5x47.5					52, 364 52, 52	52, 364 52, 52	
FLGB2377	50x50							52, 1248 36, 0
FLGA2577	52.5x52.5						0, 448 60, 60	
FLGA2892	55x55							52, 1404 48, 0

## Notes:

- Go to [Ordering Information](#) for package designation details.
- All packages have 1.0mm ball pitch.
- Packages with the same last letter and number sequence, e.g., A2104, are footprint compatible with all other UltraScale architecture-based devices with the same sequence. The footprint compatible devices within this family are outlined. See the [UltraScale Architecture Product Selection Guide](#) for details on inter-family migration.

# Virtex UltraScale+ FPGA Feature Summary

Table 9: Virtex UltraScale+ FPGA Feature Summary

	VU3P	VU5P	VU7P	VU9P	VU11P	VU13P	VU31P	VU33P	VU35P	VU37P
System Logic Cells	862,050	1,313,763	1,724,100	2,586,150	2,835,000	3,780,000	961,800	961,800	1,906,800	2,851,800
CLB Flip-Flops	788,160	1,201,154	1,576,320	2,364,480	2,592,000	3,456,000	879,360	879,360	1,743,360	2,607,360
CLB LUTs	394,080	600,577	788,160	1,182,240	1,296,000	1,728,000	439,680	439,680	871,680	1,303,680
Max. Distributed RAM (Mb)	12.0	18.3	24.1	36.1	36.2	48.3	12.5	12.5	24.6	36.7
Block RAM Blocks	720	1,024	1,440	2,160	2,016	2,688	672	672	1,344	2,016
Block RAM (Mb)	25.3	36.0	50.6	75.9	70.9	94.5	23.6	23.6	47.3	70.9
UltraRAM Blocks	320	470	640	960	960	1,280	320	320	640	960
UltraRAM (Mb)	90.0	132.2	180.0	270.0	270.0	360.0	90.0	90.0	180.0	270.0
HBM DRAM (GB)	–	–	–	–	–	–	4	8	8	8
CMTs (1 MMCM and 2 PLLs)	10	20	20	30	12	16	4	4	8	12
Max. HP I/O <sup>(1)</sup>	520	832	832	832	624	832	208	208	416	624
DSP Slices	2,280	3,474	4,560	6,840	9,216	12,288	2,880	2,880	5,952	9,024
System Monitor	1	2	2	3	3	4	1	1	2	3
GTY Transceivers 32.75Gb/s <sup>(2)</sup>	40	80	80	120	96	128	32	32	64	96
Transceiver Fractional PLLs	20	40	40	60	48	64	16	16	32	48
PCIe Gen3 x16 and Gen4 x8	2	4	4	6	3	4	4	4	5	6
CCIX Ports <sup>(3)</sup>	–	–	–	–	–	–	4	4	4	4
150G Interlaken	3	4	6	9	6	8	0	0	2	4
100G Ethernet w/RS-FEC	3	4	6	9	9	12	2	2	5	8

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. GTY transceivers in the FLGF1924 package support data rates up to 16.3Gb/s. See [Table 10](#).
3. A CCIX port requires the use of a PCIe Gen3 x16 / Gen4 x8 block.

# Virtex UltraScale+ Device-Package Combinations and Maximum I/Os

Table 10: Virtex UltraScale+ Device-Package Combinations and Maximum I/Os

Package (1)(2)(3)	Package Dimensions (mm)	VU3P	VU5P	VU7P	VU9P	VU11P	VU13P	VU31P	VU33P	VU35P	VU37P
		HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY	HP, GTY
FFVC1517	40x40	520, 40									
FLGF1924(4)	45x45					624, 64					
FLVA2104	47.5x47.5		832, 52	832, 52							
FLGA2104	47.5x47.5				832, 52						
FHGA2104	52.5x52.5(5)						832, 52				
FLVB2104	47.5x47.5		702, 76	702, 76							
FLGB2104	47.5x47.5				702, 76	572, 76					
FHGB2104	52.5x52.5(5)						702, 76				
FLVC2104	47.5x47.5		416, 80	416, 80							
FLGC2104	47.5x47.5				416, 104	416, 96					
FHGC2104	52.5x52.5(5)						416, 104				
FSGD2104	47.5x47.5				676, 76	572, 76					
FIGD2104	52.5x52.5(5)						676, 76				
FLGA2577	52.5x52.5				448, 120	448, 96	448, 128				
FSVH1924	45x45							208, 32			
FSVH2104	47.5x47.5								208, 32	416, 64	
FSVH2892	55x55									416, 64	624, 96

## Notes:

- Go to [Ordering Information](#) for package designation details.
- All packages have 1.0mm ball pitch.
- Packages with the same last letter and number sequence, e.g., A2104, are footprint compatible with all other UltraScale architecture-based devices with the same sequence. The footprint compatible devices within this family are outlined. See the [UltraScale Architecture Product Selection Guide](#) for details on inter-family migration.
- GTY transceivers in the FLGF1924 package support data rates up to 16.3Gb/s.
- These 52.5x52.5mm overhang packages have the same PCB ball footprint as the corresponding 47.5x47.5mm packages (i.e., the same last letter and number sequence) and are footprint compatible.

# Zynq UltraScale+: CG Device Feature Summary

Table 11: Zynq UltraScale+: CG Device Feature Summary

	ZU2CG	ZU3CG	ZU4CG	ZU5CG	ZU6CG	ZU7CG	ZU9CG
Application Processing Unit	Dual-core ARM Cortex-A53 MPCore with CoreSight; NEON & Single/Double Precision Floating Point; 32KB/32KB L1 Cache, 1MB L2 Cache						
Real-Time Processing Unit	Dual-core ARM Cortex-R5 with CoreSight; Single/Double Precision Floating Point; 32KB/32KB L1 Cache, and TCM						
Embedded and External Memory	256KB On-Chip Memory w/ECC; External DDR4; DDR3; DDR3L; LPDDR4; LPDDR3; External Quad-SPI; NAND; eMMC						
General Connectivity	214 PS I/O; UART; CAN; USB 2.0; I2C; SPI; 32b GPIO; Real Time Clock; WatchDog Timers; Triple Timer Counters						
High-Speed Connectivity	4 PS-GTR; PCIe Gen1/2; Serial ATA 3.1; DisplayPort 1.2a; USB 3.0; SGMII						
System Logic Cells	103,320	154,350	192,150	256,200	469,446	504,000	599,550
CLB Flip-Flops	94,464	141,120	175,680	234,240	429,208	460,800	548,160
CLB LUTs	47,232	70,560	87,840	117,120	214,604	230,400	274,080
Distributed RAM (Mb)	1.2	1.8	2.6	3.5	6.9	6.2	8.8
Block RAM Blocks	150	216	128	144	714	312	912
Block RAM (Mb)	5.3	7.6	4.5	5.1	25.1	11.0	32.1
UltraRAM Blocks	0	0	48	64	0	96	0
UltraRAM (Mb)	0	0	14.0	18.0	0	27.0	0
DSP Slices	240	360	728	1,248	1,973	1,728	2,520
CMTs	3	3	4	4	4	8	4
Max. HP I/O <sup>(1)</sup>	156	156	156	156	208	416	208
Max. HD I/O <sup>(2)</sup>	96	96	96	96	120	48	120
System Monitor	2	2	2	2	2	2	2
GTH Transceiver 16.3Gb/s <sup>(3)</sup>	0	0	16	16	24	24	24
GTY Transceivers 32.75Gb/s	0	0	0	0	0	0	0
Transceiver Fractional PLLs	0	0	8	8	12	12	12
PCIe Gen3 x16 and Gen4 x8	0	0	2	2	0	2	0
150G Interlaken	0	0	0	0	0	0	0
100G Ethernet w/ RS-FEC	0	0	0	0	0	0	0

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s. See [Table 12](#).



# Zynq UltraScale+: EG Device-Package Combinations and Maximum I/Os

Table 14: Zynq UltraScale+: EG Device-Package Combinations and Maximum I/Os

Package (1)(2)(3)(4)(5)	Package Dimensions (mm)	ZU2EG	ZU3EG	ZU4EG	ZU5EG	ZU6EG	ZU7EG	ZU9EG	ZU11EG	ZU15EG	ZU17EG	ZU19EG
		HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY	HD, HP GTH, GTY
SBVA484(6)	19x19	24, 58 0, 0	24, 58 0, 0									
SFVA625	21x21	24, 156 0, 0	24, 156 0, 0									
SFVC784(7)	23x23	96, 156 0, 0	96, 156 0, 0	96, 156 4, 0	96, 156 4, 0							
FBVB900	31x31			48, 156 16, 0	48, 156 16, 0		48, 156 16, 0					
FFVC900	31x31					48, 156 16, 0		48, 156 16, 0		48, 156 16, 0		
FFVB1156	35x35					120, 208 24, 0		120, 208 24, 0		120, 208 24, 0		
FFVC1156	35x35						48, 312 20, 0		48, 312 20, 0			
FFVB1517	40x40								72, 416 16, 0		72, 572 16, 0	72, 572 16, 0
FFVF1517	40x40						48, 416 24, 0		48, 416 32, 0			
FFVC1760	42.5x42.5								96, 416 32, 16		96, 416 32, 16	96, 416 32, 16
FFVD1760	42.5x42.5										48, 260 44, 28	48, 260 44, 28
FFVE1924	45x45										96, 572 44, 0	96, 572 44, 0

## Notes:

- Go to [Ordering Information](#) for package designation details.
- FB/FF packages have 1.0mm ball pitch. SB/SF packages have 0.8mm ball pitch.
- All device package combinations bond out 4 PS-GTR transceivers.
- All device package combinations bond out 214 PS I/O except ZU2EG and ZU3EG in the SBVA484 and SFVA625 packages, which bond out 170 PS I/Os.
- Packages with the same last letter and number sequence, e.g., A484, are footprint compatible with all other UltraScale architecture-based devices with the same sequence. The footprint compatible devices within this family are outlined.
- All 58 HP I/O pins are powered by the same V<sub>CCO</sub> supply.
- GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s.

# Zynq UltraScale+: EG Device Feature Summary

Table 15: Zynq UltraScale+: EV Device Feature Summary

	ZU4EV	ZU5EV	ZU7EV
Application Processing Unit	Quad-core ARM Cortex-A53 MPCore with CoreSight; NEON & Single/Double Precision Floating Point; 32KB/32KB L1 Cache, 1MB L2 Cache		
Real-Time Processing Unit	Dual-core ARM Cortex-R5 with CoreSight; Single/Double Precision Floating Point; 32KB/32KB L1 Cache, and TCM		
Embedded and External Memory	256KB On-Chip Memory w/ECC; External DDR4; DDR3; DDR3L; LPDDR4; LPDDR3; External Quad-SPI; NAND; eMMC		
General Connectivity	214 PS I/O; UART; CAN; USB 2.0; I2C; SPI; 32b GPIO; Real Time Clock; WatchDog Timers; Triple Timer Counters		
High-Speed Connectivity	4 PS-GTR; PCIe Gen1/2; Serial ATA 3.1; DisplayPort 1.2a; USB 3.0; SGMII		
Graphic Processing Unit	ARM Mali-400 MP2; 64KB L2 Cache		
Video Codec	1	1	1
System Logic Cells	192,150	256,200	504,000
CLB Flip-Flops	175,680	234,240	460,800
CLB LUTs	87,840	117,120	230,400
Distributed RAM (Mb)	2.6	3.5	6.2
Block RAM Blocks	128	144	312
Block RAM (Mb)	4.5	5.1	11.0
UltraRAM Blocks	48	64	96
UltraRAM (Mb)	14.0	18.0	27.0
DSP Slices	728	1,248	1,728
CMTs	4	4	8
Max. HP I/O <sup>(1)</sup>	156	156	416
Max. HD I/O <sup>(2)</sup>	96	96	48
System Monitor	2	2	2
GTH Transceiver 16.3Gb/s <sup>(3)</sup>	16	16	24
GTY Transceivers 32.75Gb/s	0	0	0
Transceiver Fractional PLLs	8	8	12
PCIe Gen3 x16 and Gen4 x8	2	2	2
150G Interlaken	0	0	0
100G Ethernet w/ RS-FEC	0	0	0

## Notes:

1. HP = High-performance I/O with support for I/O voltage from 1.0V to 1.8V.
2. HD = High-density I/O with support for I/O voltage from 1.2V to 3.3V.
3. GTH transceivers in the SFVC784 package support data rates up to 12.5Gb/s. See [Table 16](#).

contains vertical and horizontal clock routing that span its full height and width. These horizontal and vertical clock routes can be segmented at the clock region boundary to provide a flexible, high-performance, low-power clock distribution architecture. Figure 2 is a representation of an FPGA divided into regions.



Figure 2: Column-Based FPGA Divided into Clock Regions

## Processing System (PS)

Zynq UltraScale+ MPSoCs consist of a PS coupled with programmable logic. The contents of the PS varies between the different Zynq UltraScale+ devices. All devices contain an APU, an RPU, and many peripherals for connecting the multiple processing engines to external components. The EG and EV devices contain a GPU and the EV devices contain a video codec unit (VCU). The components of the PS are connected together and to the PL through a multi-layered ARM AMBA AXI non-blocking interconnect that supports multiple simultaneous master-slave transactions. Traffic through the interconnect can be regulated by the quality of service (QoS) block in the interconnect. Twelve dedicated AXI 32-bit, 64-bit, or 128-bit ports connect the PL to high-speed interconnect and DDR in the PS via a FIFO interface.

There are four independently controllable power domains: the PL plus three within the PS (full power, lower power, and battery power domains). Additionally, many peripherals support clock gating and power gating to further reduce dynamic and static power consumption.

## Application Processing Unit (APU)

The APU has a feature-rich dual-core or quad-core ARM Cortex-A53 processor. Cortex-A53 cores are 32-bit/64-bit application processors based on ARM-v8A architecture, offering the best performance-to-power ratio. The ARMv8 architecture supports hardware virtualization. Each of the Cortex-A53 cores has: 32KB of instruction and data L1 caches, with parity and ECC protection respectively; a NEON SIMD engine; and a single and double precision floating point unit. In addition to these blocks, the APU consists of a snoop control unit and a 1MB L2 cache with ECC protection to enhance system-level performance. The snoop control unit keeps the L1 caches coherent thus eliminating the need of spending software bandwidth for coherency. The APU also has a built-in interrupt controller supporting virtual interrupts. The APU communicates to the rest of the PS through 128-bit AXI coherent extension (ACE) port via Cache Coherent Interconnect (CCI) block, using the System Memory Management Unit (SMMU). The APU is also connected to the Programmable Logic (PL), through the 128-bit accelerator coherency port

(ACP), providing a low latency coherent port for accelerators in the PL. To support real-time debug and trace, each core also has an Embedded Trace Macrocell (ETM) that communicates with the ARM CoreSight™ Debug System.

## Real-Time Processing Unit (RPU)

The RPU in the PS contains a dual-core ARM Cortex-R5 PS. Cortex-R5 cores are 32-bit real-time processor cores based on ARM-v7R architecture. Each of the Cortex-R5 cores has 32KB of level-1 (L1) instruction and data cache with ECC protection. In addition to the L1 caches, each of the Cortex-R5 cores also has a 128KB tightly coupled memory (TCM) interface for real-time single cycle access. The RPU also has a dedicated interrupt controller. The RPU can operate in either split or lock-step mode. In split mode, both processors run independently of each other. In lock-step mode, they run in parallel with each other, with integrated comparator logic, and the TCMs are used as 256KB unified memory. The RPU communicates with the rest of the PS via the 128-bit AXI-4 ports connected to the low power domain switch. It also communicates directly with the PL through 128-bit low latency AXI-4 ports. To support real-time debug and trace each core also has an embedded trace macrocell (ETM) that communicates with the ARM CoreSight Debug System.

## External Memory

The PS can interface to many types of external memories through dedicated memory controllers. The dynamic memory controller supports DDR3, DDR3L, DDR4, LPDDR3, and LPDDR4 memories. The multi-protocol DDR memory controller can be configured to access a 2GB address space in 32-bit addressing mode and up to 32GB in 64-bit addressing mode using a single or dual rank configuration of 8-bit, 16-bit, or 32-bit DRAM memories. Both 32-bit and 64-bit bus access modes are protected by ECC using extra bits.

The SD/eMMC controller supports 1 and 4 bit data interfaces at low, default, high-speed, and ultra-high-speed (UHS) clock rates. This controller also supports 1-, 4-, or 8-bit-wide eMMC interfaces that are compliant to the eMMC 4.51 specification. eMMC is one of the primary boot and configuration modes for Zynq UltraScale+ MPSoCs and supports boot from managed NAND devices. The controller has a built-in DMA for enhanced performance.

The Quad-SPI controller is one of the primary boot and configuration devices. It supports 4-byte and 3-byte addressing modes. In both addressing modes, single, dual-stacked, and dual-parallel configurations are supported. Single mode supports a quad serial NOR flash memory, while in double stacked and double parallel modes, it supports two quad serial NOR flash memories.

The NAND controller is based on ONFI3.1 specification. It has an 8-pin interface and provides 200Mb/s of bandwidth in synchronous mode. It supports 24 bits of ECC thus enabling support for SLC NAND memories. It has two chip-selects to support deeper memory and a built-in DMA for enhanced performance.

## Graphics Processing Unit (GPU)

The dedicated ARM Mali-400 MP2 GPU in the PS supports 2D and 3D graphics acceleration up to 1080p resolution. The Mali-400 supports OpenGL ES 1.1 and 2.0 for 3D graphics and Open VG 1.1 standards for 2D vector graphics. It has a geometry processor (GP) and 2 pixel processors to perform tile rendering operations in parallel. It has dedicated Memory management units for GP and pixel processors, which supports 4 KB page size. The GPU also has 64KB level-2 (L2) read-only cache. It supports 4X and 16X Full scene Anti-Aliasing (FSAA). It is fully autonomous, enabling maximum parallelization between APU and GPU. It has built-in hardware texture decompression, allowing the texture to remain compressed (in ETC format) in graphics hardware and decompress the required samples on the fly. It also supports efficient alpha blending of multiple layers in hardware without additional bandwidth consumption. It has a pixel fill rate of 2Mpixel/sec/MHz and a triangle rate of 0.1Mvertex/sec/MHz. The GPU supports extensive texture format for RGBA 8888, 565, and 1556 in Mono 8, 16, and YUV formats. For power sensitive applications, the GPU supports clock and power gating for each GP, pixel processors, and L2 cache. During power gating, GPU does not consume any static or dynamic power; during clock gating, it only consumes static power.

## Video Codec Unit (VCU)

The video codec unit (VCU) provides multi-standard video encoding and decoding capabilities, including: High Efficiency Video Coding (HEVC), i.e., H.265; and Advanced Video Coding (AVC), i.e., H.264 standards. The VCU is capable of simultaneous encode and decode at rates up to 4Kx2K at 60 frames per second (fps) (approx. 600Mpixel/sec) or 8Kx4K at a reduced frame rate (~15fps).

---

## Input/Output

All UltraScale devices, whether FPGA or MPSoC, have I/O pins for communicating to external components. In addition, in the MPSoC's PS, there are another 78 I/Os that the I/O peripherals use to communicate to external components, referred to as multiplexed I/O (MIO). If more than 78 pins are required by the I/O peripherals, the I/O pins in the PL can be used to extend the MPSoC interfacing capability, referred to as extended MIO (EMIO).

The number of I/O pins in UltraScale FPGAs and in the programmable logic of UltraScale+ MPSoCs varies depending on device and package. Each I/O is configurable and can comply with a large number of I/O standards. The I/Os are classed as high-range (HR), high-performance (HP), or high-density (HD). The HR I/Os offer the widest range of voltage support, from 1.2V to 3.3V. The HP I/Os are optimized for highest performance operation, from 1.0V to 1.8V. The HD I/Os are reduced-feature I/Os organized in banks of 24, providing voltage support from 1.2V to 3.3V.

All I/O pins are organized in banks, with 52 HP or HR pins per bank or 24 HD pins per bank. Each bank has one common  $V_{CCO}$  output buffer power supply, which also powers certain input buffers. In addition, HR banks can be split into two half-banks, each with their own  $V_{CCO}$  supply. Some single-ended input buffers require an internally generated or an externally applied reference voltage ( $V_{REF}$ ).  $V_{REF}$  pins can be driven directly from the PCB or internally generated using the internal  $V_{REF}$  generator circuitry present in each bank.

# High-Speed Serial Transceivers

Serial data transmission between devices on the same PCB, over backplanes, and across even longer distances is becoming increasingly important for scaling to 100Gb/s and 400Gb/s line cards. Specialized dedicated on-chip circuitry and differential I/O capable of coping with the signal integrity issues are required at these high data rates.

Three types of transceivers are used in the UltraScale architecture: GTH and GTY in FPGAs and MPSoC PL, and PS-GTR in the MPSoC PS. All transceivers are arranged in groups of four, known as a transceiver Quad. Each serial transceiver is a combined transmitter and receiver. [Table 17](#) compares the available transceivers.

**Table 17: Transceiver Information**

	Kintex UltraScale		Kintex UltraScale+		Virtex UltraScale		Virtex UltraScale+	Zynq UltraScale+		
Type	GTH	GTY	GTH	GTY	GTH	GTY	GTY	PS-GTR	GTH	GTY
Qty	16–64	0–32	20–60	0–60	20–60	0–60	40–128	4	0–44	0–28
Max. Data Rate	16.3Gb/s	16.3Gb/s	16.3Gb/s	32.75Gb/s	16.3Gb/s	30.5Gb/s	32.75Gb/s	6.0Gb/s	16.3Gb/s	32.75Gb/s
Min. Data Rate	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	0.5Gb/s	1.25Gb/s	0.5Gb/s	0.5Gb/s
Key Apps	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>PCIe Gen2</li> <li>USB</li> <li>Ethernet</li> </ul>	<ul style="list-style-type: none"> <li>Backplane</li> <li>PCIe Gen4</li> <li>HMC</li> </ul>	<ul style="list-style-type: none"> <li>100G+ Optics</li> <li>Chip-to-Chip</li> <li>25G+ Backplane</li> <li>HMC</li> </ul>

The following information in this section pertains to the GTH and GTY only.

The serial transmitter and receiver are independent circuits that use an advanced phase-locked loop (PLL) architecture to multiply the reference frequency input by certain programmable numbers between 4 and 25 to become the bit-serial data clock. Each transceiver has a large number of user-definable features and parameters. All of these can be defined during device configuration, and many can also be modified during operation.

## Transmitter

The transmitter is fundamentally a parallel-to-serial converter with a conversion ratio of 16, 20, 32, 40, 64, or 80 for the GTH and 16, 20, 32, 40, 64, 80, 128, or 160 for the GTY. This allows the designer to trade off datapath width against timing margin in high-performance designs. These transmitter outputs drive the PC board with a single-channel differential output signal. TXOUTCLK is the appropriately divided serial data clock and can be used directly to register the parallel data coming from the internal logic. The incoming parallel data is fed through an optional FIFO and has additional hardware support for the 8B/10B, 64B/66B, or 64B/67B encoding schemes to provide a sufficient number of transitions. The bit-serial output signal drives two package pins with differential signals. This output signal pair has programmable signal swing as well as programmable pre- and post-emphasis to compensate for PC board losses and other interconnect characteristics. For shorter channels, the swing can be reduced to reduce power consumption.

## Receiver

The receiver is fundamentally a serial-to-parallel converter, changing the incoming bit-serial differential signal into a parallel stream of words, each 16, 20, 32, 40, 64, or 80 bits in the GTH or 16, 20, 32, 40, 64, 80, 128, or 160 for the GTY. This allows the designer to trade off internal datapath width against logic timing margin. The receiver takes the incoming differential data stream, feeds it through programmable DC automatic gain control, linear and decision feedback equalizers (to compensate for PC board, cable, optical and other interconnect characteristics), and uses the reference clock input to initiate clock recognition. There is no need for a separate clock line. The data pattern uses non-return-to-zero (NRZ) encoding and optionally ensures sufficient data transitions by using the selected encoding scheme. Parallel data is then transferred into the device logic using the RXUSRCLK clock. For short channels, the transceivers offer a special low-power mode (LPM) to reduce power consumption by approximately 30%. The receiver DC automatic gain control and linear and decision feedback equalizers can optionally “auto-adapt” to automatically learn and compensate for different interconnect characteristics. This enables even more margin for 10G+ and 25G+ backplanes.

## Out-of-Band Signaling

The transceivers provide out-of-band (OOB) signaling, often used to send low-speed signals from the transmitter to the receiver while high-speed serial data transmission is not active. This is typically done when the link is in a powered-down state or has not yet been initialized. This benefits PCIe and SATA/SAS and QPI applications.

## Block RAM

Every UltraScale architecture-based device contains a number of 36 Kb block RAMs, each with two completely independent ports that share only the stored data. Each block RAM can be configured as one 36Kb RAM or two independent 18Kb RAMs. Each memory access, read or write, is controlled by the clock. Connections in every block RAM column enable signals to be cascaded between vertically adjacent block RAMs, providing an easy method to create large, fast memory arrays, and FIFOs with greatly reduced power consumption.

All inputs, data, address, clock enables, and write enables are registered. The input address is always clocked (unless address latching is turned off), retaining data until the next operation. An optional output data pipeline register allows higher clock rates at the cost of an extra cycle of latency. During a write operation, the data output can reflect either the previously stored data or the newly written data, or it can remain unchanged. Block RAM sites that remain unused in the user design are automatically powered down to reduce total power consumption. There is an additional pin on every block RAM to control the dynamic power gating feature.

## Programmable Data Width

Each port can be configured as  $32K \times 1$ ;  $16K \times 2$ ;  $8K \times 4$ ;  $4K \times 9$  (or 8);  $2K \times 18$  (or 16);  $1K \times 36$  (or 32); or  $512 \times 72$  (or 64). Whether configured as block RAM or FIFO, the two ports can have different aspect ratios without any constraints. Each block RAM can be divided into two completely independent 18Kb block RAMs that can each be configured to any aspect ratio from  $16K \times 1$  to  $512 \times 36$ . Everything described previously for the full 36Kb block RAM also applies to each of the smaller 18Kb block RAMs. Only in simple dual-port (SDP) mode can data widths of greater than 18bits (18Kb RAM) or 36 bits (36Kb RAM) be accessed. In this mode, one port is dedicated to read operation, the other to write operation. In SDP mode, one side (read or write) can be variable, while the other is fixed to 32/36 or 64/72. Both sides of the dual-port 36Kb RAM can be of variable width.

## Error Detection and Correction

Each 64-bit-wide block RAM can generate, store, and utilize eight additional Hamming code bits and perform single-bit error correction and double-bit error detection (ECC) during the read process. The ECC logic can also be used when writing to or reading from external 64- to 72-bit-wide memories.

## FIFO Controller

Each block RAM can be configured as a 36Kb FIFO or an 18Kb FIFO. The built-in FIFO controller for single-clock (synchronous) or dual-clock (asynchronous or multirate) operation increments the internal addresses and provides four handshaking flags: full, empty, programmable full, and programmable empty. The programmable flags allow the user to specify the FIFO counter values that make these flags go active. The FIFO width and depth are programmable with support for different read port and write port widths on a single FIFO. A dedicated cascade path allows for easy creation of deeper FIFOs.



---

## UltraRAM

UltraRAM is a high-density, dual-port, synchronous memory block available in UltraScale+ devices. Both of the ports share the same clock and can address all of the 4K x 72 bits. Each port can independently read from or write to the memory array. UltraRAM supports two types of write enable schemes. The first mode is consistent with the block RAM byte write enable mode. The second mode allows gating the data and parity byte writes separately. UltraRAM blocks can be connected together to create larger memory arrays. Dedicated routing in the UltraRAM column enables the entire column height to be connected together. If additional density is required, all the UltraRAM columns in an SLR can be connected together with a few fabric resources to create single instances of RAM approximately 100Mb in size. This makes UltraRAM an ideal solution for replacing external memories such as SRAM. Cascadable anywhere from 288Kb to 100Mb, UltraRAM provides the flexibility to fulfill many different memory requirements.

## Error Detection and Correction

Each 64-bit-wide UltraRAM can generate, store and utilize eight additional Hamming code bits and perform single-bit error correction and double-bit error detection (ECC) during the read process.

---

## High Bandwidth Memory (HBM)

Virtex UltraScale+ HBM devices incorporate 4GB HBM stacks adjacent to the FPGA die. Using stacked silicon interconnect technology, the FPGA communicates to the HBM stacks through memory controllers that connect to dedicated low-inductance interconnect in the silicon interposer. Each Virtex UltraScale+ HBM FPGA contains one or two HBM stacks, resulting in up to 8GB of HBM per FPGA.

The FPGA has 32 HBM AXI interfaces used to communicate with the HBM. Through a built-in switch mechanism, any of the 32 HBM AXI interfaces can access any memory address on either one or both of the HBM stacks due to the flexible addressing feature. This flexible connection between the FPGA and the HBM stacks results in easy floorplanning and timing closure. The memory controllers perform read and write reordering to improve bus efficiency. Data integrity is ensured through error checking and correction (ECC) circuitry.

---

## Configurable Logic Block

Every Configurable Logic Block (CLB) in the UltraScale architecture contains 8 LUTs and 16 flip-flops. The LUTs can be configured as either one 6-input LUT with one output, or as two 5-input LUTs with separate outputs but common inputs. Each LUT can optionally be registered in a flip-flop. In addition to the LUTs and flip-flops, the CLB contains arithmetic carry logic and multiplexers to create wider logic functions.

Each CLB contains one slice. There are two types of slices: SLICEL and SLICEM. LUTs in the SLICEM can be configured as 64-bit RAM, as 32-bit shift registers (SRL32), or as two SRL16s. CLBs in the UltraScale architecture have increased routing and connectivity compared to CLBs in previous-generation Xilinx devices. They also have additional control signals to enable superior register packing, resulting in overall higher device utilization.

---

## Interconnect

Various length vertical and horizontal routing resources in the UltraScale architecture that span 1, 2, 4, 5, 12, or 16 CLBs ensure that all signals can be transported from source to destination with ease, providing support for the next generation of wide data buses to be routed across even the highest capacity devices while simultaneously improving quality of results and software run time.

---

## Digital Signal Processing

DSP applications use many binary multipliers and accumulators, best implemented in dedicated DSP slices. All UltraScale devices have many dedicated, low-power DSP slices, combining high speed with small size while retaining system design flexibility.

Each DSP slice fundamentally consists of a dedicated  $27 \times 18$  bit twos complement multiplier and a 48-bit accumulator. The multiplier can be dynamically bypassed, and two 48-bit inputs can feed a single-instruction-multiple-data (SIMD) arithmetic unit (dual 24-bit add/subtract/accumulate or quad 12-bit add/subtract/accumulate), or a logic unit that can generate any one of ten different logic functions of the two operands.

The DSP includes an additional pre-adder, typically used in symmetrical filters. This pre-adder improves performance in densely packed designs and reduces the DSP slice count by up to 50%. The 96-bit-wide XOR function, programmable to 12, 24, 48, or 96-bit widths, enables performance improvements when implementing forward error correction and cyclic redundancy checking algorithms.

The DSP also includes a 48-bit-wide pattern detector that can be used for convergent or symmetric rounding. The pattern detector is also capable of implementing 96-bit-wide logic functions when used in conjunction with the logic unit.

The DSP slice provides extensive pipelining and extension capabilities that enhance the speed and efficiency of many applications beyond digital signal processing, such as wide dynamic bus shifters, memory address generators, wide bus multiplexers, and memory-mapped I/O register files. The accumulator can also be used as a synchronous up/down counter.

---

## System Monitor

The System Monitor blocks in the UltraScale architecture are used to enhance the overall safety, security, and reliability of the system by monitoring the physical environment via on-chip power supply and temperature sensors and external channels to the ADC.

All UltraScale architecture-based devices contain at least one System Monitor. The System Monitor in UltraScale+ FPGAs and the PL of Zynq UltraScale+ MPSoCs is similar to the Kintex UltraScale and Virtex UltraScale devices but with additional features including a PMBus interface.

The ordering information shown in [Figure 3](#) applies to all packages in the Kintex UltraScale and Virtex UltraScale FPGAs. Refer to the Package Marking section of [UG575, UltraScale and UltraScale+ FPGAs Packaging and Pinouts User Guide](#) for a more detailed explanation of the device markings.



**Figure 3: Kintex UltraScale and Virtex UltraScale FPGA Ordering Information**

# Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
02/15/2017	2.11	Updated <a href="#">Table 1</a> , <a href="#">Table 9</a> : Converted HBM from Gb to GB. Updated <a href="#">Table 11</a> , <a href="#">Table 13</a> , and <a href="#">Table 15</a> : Updated DSP count for Zynq UltraScale+ MPSoCs. Updated <a href="#">Cache Coherent Interconnect for Accelerators (CCIX)</a> . Updated <a href="#">High Bandwidth Memory (HBM)</a> . Updated <a href="#">Table 21</a> : Added -2E speed grade to all UltraScale+ devices. Removed -3E from XCZU2 and XCZU3.
11/09/2016	2.10	Updated <a href="#">Table 1</a> . Added HBM devices to <a href="#">Table 9</a> , <a href="#">Table 10</a> , <a href="#">Table 19</a> and new <a href="#">High Bandwidth Memory (HBM)</a> section. Added <a href="#">Cache Coherent Interconnect for Accelerators (CCIX)</a> section.
09/27/2016	2.9	Updated <a href="#">Table 5</a> , <a href="#">Table 12</a> , <a href="#">Table 13</a> , and <a href="#">Table 14</a> .
06/03/2016	2.8	Added Zynq UltraScale+ MPSoC CG devices: Added <a href="#">Table 2</a> . Updated <a href="#">Table 11</a> , <a href="#">Table 12</a> , <a href="#">Table 21</a> , and <a href="#">Figure 5</a> . Created separate tables for EG and EV devices: <a href="#">Table 13</a> , <a href="#">Table 14</a> , <a href="#">Table 15</a> , and <a href="#">Table 16</a> . Updated <a href="#">Table 1</a> , <a href="#">Table 3</a> , <a href="#">Table 5</a> and notes, <a href="#">Table 6</a> and notes, <a href="#">Table 7</a> , <a href="#">Table 9</a> , <a href="#">Table 10</a> , <a href="#">Processing System Overview</a> , and <a href="#">Processing System (PS)</a> details.
02/17/2016	2.7	Added <a href="#">Migrating Devices</a> . Updated <a href="#">Table 4</a> , <a href="#">Table 5</a> , <a href="#">Table 6</a> , <a href="#">Table 10</a> , <a href="#">Table 11</a> , <a href="#">Table 12</a> , and <a href="#">Figure 4</a> .
12/15/2015	2.6	Updated <a href="#">Table 1</a> , <a href="#">Table 5</a> , <a href="#">Table 6</a> , <a href="#">Table 9</a> , <a href="#">Table 12</a> , and <a href="#">Configuration</a> .
11/24/2015	2.5	Updated <a href="#">Configuration, Encryption, and System Monitoring</a> , <a href="#">Table 5</a> , <a href="#">Table 9</a> , <a href="#">Table 11</a> , and <a href="#">Table 21</a> .
10/15/2015	2.4	Updated <a href="#">Table 1</a> , <a href="#">Table 3</a> , <a href="#">Table 5</a> , <a href="#">Table 7</a> , <a href="#">Table 9</a> , and <a href="#">Table 11</a> with System Logic Cells. Updated <a href="#">Figure 3</a> . Updated <a href="#">Table 19</a> .
09/29/2015	2.3	Added A1156 to KU095 in <a href="#">Table 4</a> . Updated <a href="#">Table 5</a> . Updated Max. Distributed RAM in <a href="#">Table 9</a> . Updated Distributed RAM in <a href="#">Table 11</a> . Added <a href="#">Table 19</a> . Updated <a href="#">Table 21</a> . Updated <a href="#">Figure 3</a> .
08/14/2015	2.2	Updated <a href="#">Table 1</a> . Added XCKU025 to <a href="#">Table 3</a> , <a href="#">Table 4</a> , and <a href="#">Table 21</a> . Updated <a href="#">Table 7</a> , <a href="#">Table 9</a> , <a href="#">Table 11</a> , <a href="#">Table 12</a> , <a href="#">Table 18</a> . Updated <a href="#">System Monitor</a> . Added voltage information to <a href="#">Table 21</a> .
04/27/2015	2.1	Updated <a href="#">Table 1</a> , <a href="#">Table 3</a> , <a href="#">Table 4</a> , <a href="#">Table 5</a> , <a href="#">Table 6</a> , <a href="#">Table 7</a> , <a href="#">Table 10</a> , <a href="#">Table 11</a> , <a href="#">Table 12</a> , <a href="#">Table 17</a> , I/O, Transceiver, PCIe, 100G Ethernet, and 150G Interlaken, <a href="#">Integrated Interface Blocks for PCI Express Designs</a> , USB 3.0/2.0, Clock Management, System Monitor, and <a href="#">Figure 3</a> .
02/23/2015	2.0	UltraScale+ device information (Kintex UltraScale+ FPGA, Virtex UltraScale+ FPGA, and Zynq UltraScale+ MPSoC) added throughout document.
12/16/2014	1.6	Updated <a href="#">Table 1</a> ; I/O, Transceiver, PCIe, 100G Ethernet, and 150G Interlaken; <a href="#">Table 3</a> , <a href="#">Table 7</a> ; <a href="#">Table 8</a> ; and <a href="#">Table 17</a> .
11/17/2014	1.5	Updated I/O, Transceiver, PCIe, 100G Ethernet, and 150G Interlaken; <a href="#">Table 1</a> ; <a href="#">Table 4</a> ; <a href="#">Table 7</a> ; <a href="#">Table 8</a> ; <a href="#">Table 17</a> ; <a href="#">Input/Output</a> ; and <a href="#">Figure 3</a> .
09/16/2014	1.4	Updated Logic Cell information in <a href="#">Table 1</a> . Updated <a href="#">Table 3</a> ; I/O, Transceiver, PCIe, 100G Ethernet, and 150G Interlaken; <a href="#">Table 7</a> ; <a href="#">Table 8</a> ; <a href="#">Integrated Block for 100G Ethernet</a> ; and <a href="#">Figure 3</a> .
05/20/2014	1.3	Updated <a href="#">Table 8</a> .
05/13/2014	1.2	Added <a href="#">Ordering Information</a> . Updated <a href="#">Table 1</a> , <a href="#">Clocks and Memory Interfaces</a> , <a href="#">Table 3</a> , <a href="#">Table 7</a> (removed XCVU145; added XCVU190), <a href="#">Table 8</a> (removed XCVU145; removed FLVD1924 from XCVU160; added XCVU190; updated Table Notes), <a href="#">Table 17</a> , <a href="#">Integrated Interface Blocks for PCI Express Designs</a> , and <a href="#">Integrated Block for Interlaken</a> , and <a href="#">Memory Interfaces</a> .

Date	Version	Description of Revisions
02/06/2014	1.1	Updated PCIe information in <a href="#">Table 1</a> and <a href="#">Table 3</a> . Added FFVJ1924 package to <a href="#">Table 8</a> .
12/10/2013	1.0	Initial Xilinx release.